



**DEFENSE LOGISTICS AGENCY**  
 LAND AND MARITIME  
 POST OFFICE BOX 3990  
 COLUMBUS, OH 43218-3990

IN REPLY  
 REFER TO

DLA LAND AND MARITIME-VQ (VQE-11-021704/Mr. Puckett/614-692-0625/rp)

3 January 2011

SUBJECT: Notification of Qualification, MIL-PRF-31032; FSC 5998; CAGE Code 3CP65

Mr. Harland Kooda  
 Pro-Tech Interconnect Solutions  
 4300 Peavey Road  
 Chaska, MN 55318-2351

Dear Mr. Kooda:

Qualification of products is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and /2. The capabilities qualified for each base material and slash sheet indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is 3 January 2011.

<b>MANUFACTURER INFORMATION</b>  Pro-Tech Interconnect Solutions 4300 Peavey Road Chaska, MN 55318-2351	<b>BASIC PLANT LOCATION</b>  Same	<b>CONTACT: Mr. Harland Kooda</b> PHONE: (952) 442-2189 FAX: (952) 442-2472 CAGE CODE: 3CP65
<b>CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:</b> MIL-PRF-31032 /1, /2 Base Materials                      GI (Woven E-Glass, Polyimide resin) Max. Panel Size                      18" X 24" Number of Layers                      10 Max. Board Thickness                0.100" Min. Thru Hole (Drilled)            0.024" Aspect Ratio                            4:1 Min. Conductor Width                0.005" Min. Conductor Spacing              0.005" Hole Preparation                      Plasma Desmear, Etchback Hole Wall Conductive Coating        Direct Metallization Copper Plating Method                Direct Current Plate Hole Fill / Via Plug                    N/A Solder Resist                            LPI Finish System                            HASL Additional Fabrication Capabilities    N/A Controlled Impedance                N/A		<b>QUALIFICATION LETTERS:</b>  VQE-11-021704

CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE: MIL-PRF-31032 /1, /2		QUALIFICATION LETTERS:
Base Materials	GF (Woven E-Glass, Epoxy resin)	VQE-11-021704
Max. Panel Size	18" X 24"	
Number of Layers	10	
Max. Board Thickness	0.100"	
Min. Thru Hole (Drilled)	0.024"	
Aspect Ratio	4:1	
Min. Conductor Width	0.005"	
Min. Conductor Spacing	0.005"	
Hole Preparation	Plasma Desmear, Etchback	
Hole Wall Conductive Coating	Direct Metallization	
Copper Plating Method	Direct Current Plate	
Hole Fill / Via Plug	N/A	
Solder Resist	LPI	
Finish System	HASL	
Additional Fabrication Capabilities	N/A	
Controlled Impedance	N/A	

Test report number 31032-3119-11 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this Office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. If you have any questions, please contact Mr. Robert Puckett, (614) 692-0625 or [vqe.rp@dla.mil](mailto:vqe.rp@dla.mil).

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualification Division

Visit us on the web at [www.dscc.dla.mil/offices/sourcing\\_and\\_qualification](http://www.dscc.dla.mil/offices/sourcing_and_qualification)